

Based on its patented multilayer low loss organic (MLO™) technology. These new capacitors represent a paradigm shift from traditional ceramic and thin film passive SMD components. Multilayer Organic Capacitors (MLOC) are polymer based capacitors that use high conductivity copper interconnects in a multilayer fashion. The ability to fabricate these components on large area substrates and state of the art laser direct imaging allow for improved cost benefits and tolerance control. The end result is a state of the art low ESR and high SRF low profile RF capacitor that can support frequencies well above one GHz. Additionally MLOCs are expansion matched to printed circuit boards to allow for improved reliability.

FEATURES

- Low ESR
- Hi-Q®

Temperature Coefficient Code

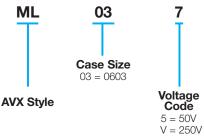
 $1 = 0 \pm 30 \text{ppm}$

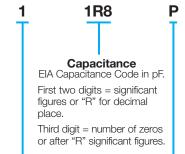
- High Self Resonance
- Tight Tolerance

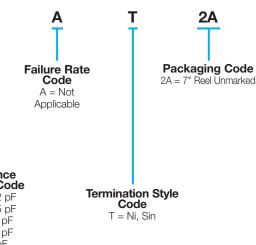
APPLICATIONS

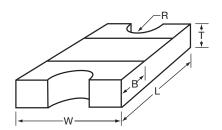
- RF Power Amplifiers
- Low Noise Amplifiers
- Filter Networks

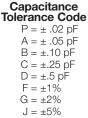
















MECHANICAL DIMENSIONS: inches (millimeters)

7 = 500V

Case	Length (L)	Width (W)	Thickness (T)	Band Width (B)	Castellation Radius (R)
0603	0.063 ± 0.004 (1.600 ± 0.102)	0.033 ± 0.004 (0.838 ± 0.102)	0.025 ± 0.004 (0.635 ± 0.102)	0.015 ± 0.005 (0.381 ± 0.127)	0.008 ± 0.002 (0.203 ± 0.051)

TAPE & REEL: All tape and reel specifications are in compliance with EIA RS481 (equivalent to IEC 286 part 3).

-8mm carrier

-7" reel, 3,000 pcs per reel





ENVIRONMENTAL CHARACTERISTICS

TEST	CONDITIONS	REQUIREMENT
Life (Endurance) MIL-STD-202F Method 108A	125°C, 2U _R , 1000 hours	No visible damage ΔC/C ≤2% for C≥5pF ΔC/C ≤0.25pF for C<5pF
Accelerated Damp Heat Steady State MIL-STD-202F Method 103B	85°C, 85% RH, U _R , 1000 hours	No visible damage ΔC/C ≤2% for C≥5pF ΔC/C ≤0.25pF for C<5pF
Temperature Cycling MIL-STD-202F Method 107E MIL-STD-883D Method 1010.7	–55°C to +125°C, 15 cycles – MLO™	No visible damage ΔC/C ≤2% for C≥5pF ΔC/C ≤0.25pF for C<5pF
Resistance to Solder Heat IEC-68-2-58	260°C ± 5°C for 10 secs.	C remains within initial limits

MECHANICAL SPECIFICATIONS

TEST	CONDITIONS	REQUIREMENT	
Solderability IEC-68-2-58	Components completely immersed in a solder bath at 235°C for 2 secs.	Terminations to be well tinned, minimum 95% coverage	
Leach Resistance IEC-68-2-58	Components completely immersed in a solder bath at 260±5°C for 60 secs.	Dissolution of termination faces ≤15% of area Dissolution of termination edges ≤25% of length	
Adhesion MIL-STD-202F Method 211A	A force of 5N applied for 10 secs.	No visible damage	
Termination Bond Strength IEC-68-2-21 Amend. 2	Tested as shown in diagram	No visible damage ΔC/C ≤2% for C≥5pF ΔC/C ≤0.25pF for C<5pF	
Robustness of Termination IEC-68-2-21 Amend. 2	A force of 5N applied for 10 secs.	No visible damage	
Storage	12 months minimum with components stored in "as received" packaging	Good solderability	

QUALITY & RELIABILITY

MLO™ capacitors utilize high density interconnect wiring technology on well established low loss organic materials.

FINAL QUALITY INSPECTION

Finished parts are tested for standard electrical parameters and visual/mechanical characteristics. Each production lot is 100% evaluated for: capacitance and proof voltage at 2.5 U_R. In addition, production is periodically evaluated for:

- Average capacitance with histogram printout for capacitance distribution;
- IR and Breakdown Voltage distribution;
- Temperature Coefficient;

- Solderability;
- · Dimensional, mechanical and temperature stability.

QUALITY ASSURANCE

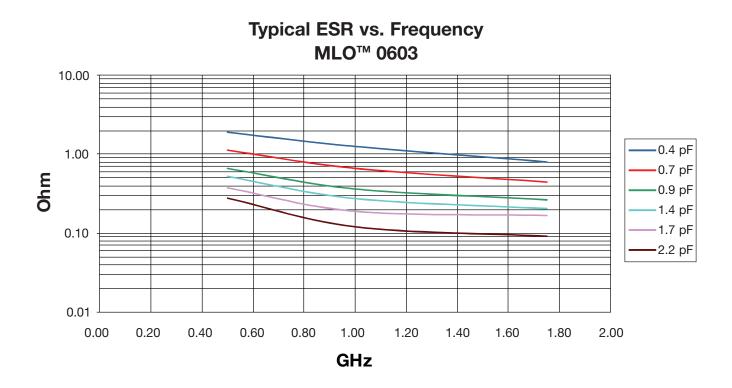
The reliability of these multilayer organic capacitors has been extensively studied. Various methods and standards have been used to ensure a high quality component including JEDEC, Mil Spec and IPC testing. AVX's quality assurance policy is based on well established international industry standards. The reliability of the capacitors is determined by accelerated testing under the following conditions:

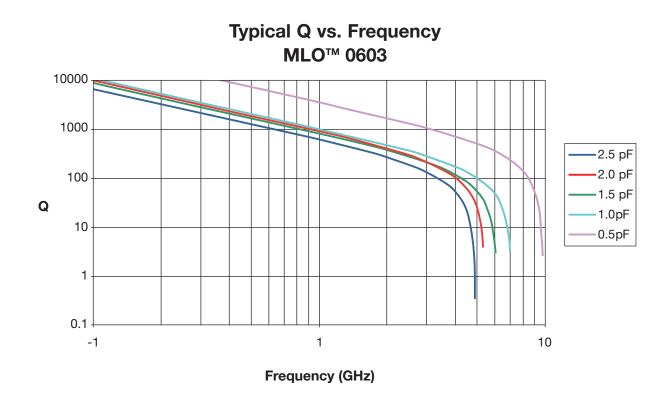
Life (Endurance)	125°C, 2U _R , 1000 hours		
Accelerated Damp Heat Steady State	85°C, 85% RH, U _R , 1000 hours.		

TABLE I: CASE SIZE ML03

Cap. pF	Cap. Tol.	WVDC	Cap. pF	Cap. Tol.	WVDC
0.1	P, A, B	50, 250, 500	1.3	P, A, B, C	50, 250, 500
0.2	P, A, B	50, 250, 500	1.4	P, A, B, C	50, 250, 500
0.3	P, A, B	50, 250, 500	1.5	P, A, B, C	50, 250, 500
0.4	P, A, B	50, 250, 500	1.6	P, A, B, C	50, 250, 500
0.5	P, A, B, C	50, 250, 500	1.7	P, A, B, C	50, 250, 500
0.6	P, A, B, C	50, 250, 500	1.8	P, A, B, C	50, 250, 500
0.7	P, A, B, C	50, 250, 500	1.9	P, A, B, C	50, 250, 500
0.8	P, A, B, C	50, 250, 500	2.0	P, A, B, C	50, 250, 500
0.9	P, A, B, C	50, 250, 500	2.2	P, A, B, C	50, 250, 500
1.0	P, A, B, C	50, 250, 500	2.4	P, A, B, C	50, 250, 500
1.1	P, A, B, C	50, 250, 500	2.5	P, A, B, C	50, 250, 500
1.2	P, A, B, C	50, 250, 500		•	











Typical Self Resonant Frequency vs. Capacitance **MLO™** 0603

